

ADHESIVE COMPOSITIONS CONTAINING ORGANIC SPACERS AND METHODS FOR USE THEREOF

ABSTRACT

In accordance with the present invention, there are provided adhesive compositions and methods for use thereof, comprising at least one maleimide-containing monomer, at least one cure initiator, and a plurality of spacer elements constructed from one or more organic polymers. Invention adhesive compositions are useful for controlling bond line thickness and planarity between a device and a substrate. Bond line thickness and planarity is largely determined by the size of the spacer elements in the adhesive composition.

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